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(54) PHOTORESISTIVE CONDUCTIVE PASTE

(57) Abstract:

PROBLEM TO BE SOLVED: To form a fine and low-resistant circuit pattern by including one or more kinds of conductive powder selected from group of Au, Ag, Pd and Pt, an acrylic group copolymer having an acid value in a specified range, a photo-reactive compound and a photo-polymerization initiator.

SOLUTION: A predetermined quantity of one to three kinds of conductive powder selected from Au, Ag, Pd and Pt, an acrylic group copolymer having an acid value at 40-200, a photo-reactive compound and glass filer are prepared. The predetermined quantity of a metal oxide

and a photo-polymerization initiator are added to the described material, and they are mixed and dispersed so as to obtain the paste, and this paste is set-solid on an alumina board, to which a surface treatment is performed, for printing, and thereafter dried. Exposure is performed by using a chrome mask formed with a fine pattern, and development and washing are performed, and thereafter, it is burned at 500°C, and sintered at 800-1000°C. A fine and a low-resistant circuit pattern, which has a film thickness at 12-20 µm, a resolution at 10-60 µm and a specific resistance at 3-18 µΩ.cm, is thereby obtained.

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